



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  <i>* : Required Field</i>

<b>Supplier Information</b>			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-01-03
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Giovanni Giacobello	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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<b>Legal Statement</b>			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
BUL743	TLDZ*IV9136F	A	998G	2017-01-03
Amount	UoM	Unit type	ST ECOPACK Grade	
1900.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10-9.1-4.5	3	THROUGH HOLE	
Comment	TO 220 AB NON ISOL			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 5th August 2016			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			TRUE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			FALSE
Substance	amount in product (mg)	Application	ppm in product
Nickel	6.00	Die / Leadframe	3159
Lead	10.62	Dsoft solder	5590

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	TLDZ*IV9136F					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	11.430	mg	supplier	die	Silicon (Si)	7440-21-3		10.999	mg	962292	5789
				supplier	metallization	Aluminium (Al)	7429-90-5		0.151	mg	13211	79
				supplier	Passivation	Silicon Oxide	7631-86-9		0.173	mg	15136	91
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.006	mg	524	3
				supplier	back side metallization	Gold (Au)	7440-57-5		0.018	mg	1575	9
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.083	mg	7262	44
Leadframe	Copper & its alloys	1258.924	mg	supplier	alloy	Copper (Cu)	7440-50-8		1251.376	mg	994004	658619
				supplier	alloy	Iron (Fe)	7439-89-6		1.253	mg	995	659
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.376	mg	299	198
				supplier	metallization	Nickel (Ni)	7440-02-0		5.919	mg	4702	3115
Soft solder	Solder	11.121	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	10.621	mg	955040	5590
				supplier	solder	Silver (Ag)	7440-22-4		0.278	mg	24998	146
				supplier	solder	Tin (Sn)	7440-31-5		0.222	mg	19962	117
Bonding wires	Other inorganic materials	3.971	mg	supplier	wire	Aluminium (Al)	7429-90-5		3.971	mg	1000000	2090
Encapsulation	Other Organic Materials	608.192	mg	supplier	mold compound	Silica, vitreous	60676-86-0		529.127	mg	870000	278488
				supplier	mold compound	Epoxy resin	25068-38-6		60.819	mg	100000	32010
				supplier	mold compound	Phenol resin	29690-82-2		15.205	mg	25000	8003
				supplier	mold compound	Carbon Black	1333-86-4		3.041	mg	5000	1601
Connections coating	Solder	6.362	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.362	mg	1000000	3348